

PATENT  
Docket No.: M4065.0135/P135

# 41A  
5-26-00  
R. Dinkler

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
Terry Gilton et al.

Serial No.: 09/285,668



Group Art Unit: 2814

Filed: April 5, 1999

Examiner: T. Quach

For: METHOD OF FORMING A  
METAL SEED LAYER FOR  
SUBSEQUENT PLATING

Assistant Commissioner for Patents  
Washington, D.C. 20231

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MAY 23 2000  
TECHNOLOGY CENTER 2800

AMENDMENT

Dear Sir:

In response to the Office Action dated February 15, 2000, please amend the above-identified U.S. patent application as follows:

In the Claims:

Please amend the claims as follows:

1. (Amended) A method of plating a metal layer on a substrate, comprising the steps of:

providing a substrate;

forming a barrier layer, containing a reducing agent, on a top surface of the

substrate;

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